

# Application Specific Discretes A.S.D.<sup>™</sup>

# 10-BIT WIDE EMI FILTER INCUDING ESD PROTECTION

#### MAIN APPLICATIONS

Where EMI filtering in ESD sensitive equipment is required : Computers and printers

- Computers and printers
  Communication systems
- Communication syste
- Mobile phones
- MCU Boards

## DESCRIPTION

The EMIF02-600FU7 is a highly integrated array designed to suppress EMI / RFI noise in all systems subjected to electromagnetic interferences.

Additionally, this filter includes an ESD protection circuitry which prevents the protected device from destruction when subjected to ESD surges up to 15 kV. The EMIF02-600FU7 provides best efficiency when using separated inputs and outputs, in the so-called 4-points structure.

## BENEFITS

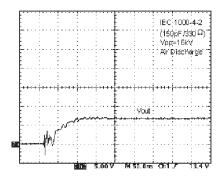
- 10-bit EMI bi-directional low-pass-filter
- Enhanced ESD protection for the protected device, optimized by the four point structure
- High flexibility in the design of high density boards

### COMPLIES WITH THE FOLLOWING STANDARDS :

IEC 1000-4-2

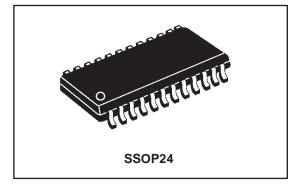
15kV (air discharge) 8 kV (contact discharge)

#### ESD response to IEC1000-4-2 (15 kV air discharge)

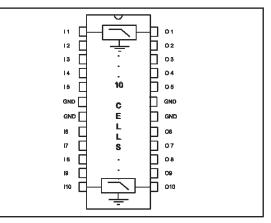


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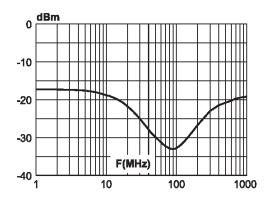
September 1998 - Ed: 2A



#### **FUNCTIONAL DIAGRAM**



#### Filtering response (with 50 $\Omega$ line)



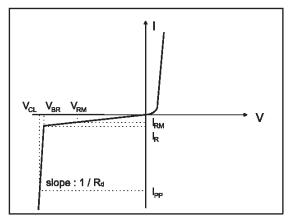
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Symbol	Parameter and test conditions	Value	Unit
V <sub>PP</sub>	ESD discharge IEC1000-4-2, air discharge ESD discharge IEC1000-4-2, contact discharge	16 9	kV
Tj	Junction temperature	150	°C
T <sub>op</sub>	Operating temperature range	-40 to + 85	°C
T <sub>stg</sub>	Storage temperature range	-55 to +150	°C
TL	Lead solder temperature (10 second duration)	260	°C

# ABSOLUTE MAXIMUM RATINGS (T<sub>amb</sub> = 25 °C)

# ELECTRICAL CHARACTERISTICS (Tamb = 25 °C)

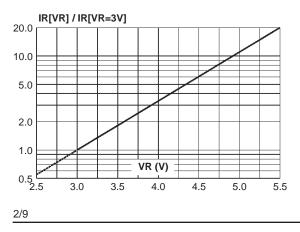
Symbol	Parameter		
V <sub>BR</sub>	Breakdown voltage		
I <sub>RM</sub>	Leakage current @ V <sub>RM</sub>		
V <sub>RM</sub>	Stand-off voltage		
Vcl	Clamping voltage		
Rd	Dynamic impedance		
IPP	Peak pulse current		
Ri/o	Serial resistance between Input and Output		



Symbol	Test conditions	Min.	Тур.	Max.	Unit
V <sub>BR</sub>	I <sub>R</sub> = 1 mA	6	7	8	V
I <sub>RM</sub>	V <sub>RM</sub> = 3V			1	μΑ
Rı/o	Serial resistance between Input and Output	480	600	720	Ω
R <sub>d</sub>	$I_{pp} = 10 \text{ A}, t_p = 2.5 \mu\text{s}$ (see note 1)		0.55		Ω

Note 1 : to calculate the ESD residual voltage, please refer to the paragraph "ESD PROTECT ION" on pages 4 & 5

**Fig.1**: Relative variation of leakage current versus reverse voltage(Typical values)





## **TECHNICAL INFORMATION**

## **FREQUENCY BEHAVIOR**

The EMIF02-600FU7 is firstly designed as an EMI/RFI filter. This low-pass filter is characterized by the following parameters:

- Cut-off frequency
- Insertion loss
- High frequency rejection

FigA1: EMIF02-600FU7 frequency response curve.

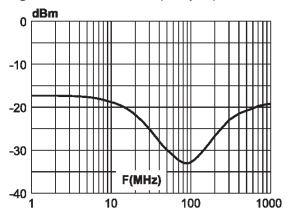
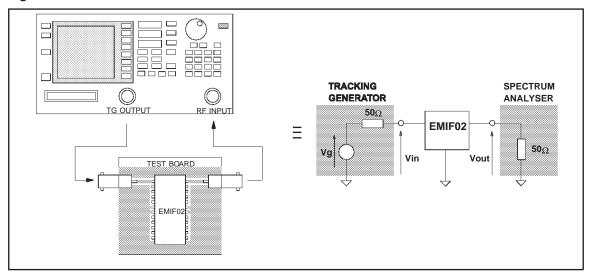


Figure A1 gives these parameters, in particular the signal rejection at the GSM frequency is about -20dBm at 900MHz, while the attenuation for FM broadcast range (around 100MHz) is better than -32dBm



#### Fig A2 : Measurement conditions

### ESD PROTECTION

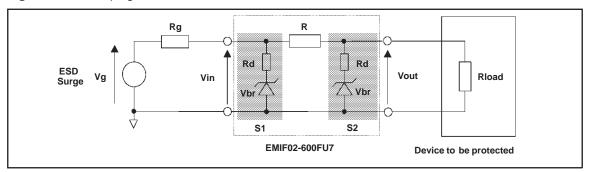
In addition to its filtering function, the EMIF02-600FU7 is particularly optimized to perform ESD protection.

ESD protection is based on voltage clamping which can be calculated by :

$$V_{CL} = V_{BR} + R_{d} I_{PP}$$

This protection function is splitted in 2 stages. As shown in figure A3, the ESD strikes are clamped by the first stage S1 and then its remaining overvoltage is applied to the second stage through the resistor R. Such a configuration makes the output voltage  $V_{out}$  very low.

#### Fig A3 : ESD clamping behavior



To have a good approximation of the remaining voltages at both Vin and Vout stages, we provide the typical dynamical resistance value Rd. By taking into account these following hypothesis : R>>Rd, RG>>Rd and Rload>>Rd, it gives these formulas:

$$Vin = \frac{Rg.Vbr+Rd.Vg}{Rg}$$
$$Vout = \frac{R.Vbr+Rd.Vin}{R}$$

The results of the calculation done for V<sub>G</sub>=8kV, R<sub>G</sub>=330Ω (IEC1000-4-2 standard) and V<sub>BR</sub>=7V (typ.) give:

#### <u>Vout = 7.01 V</u>

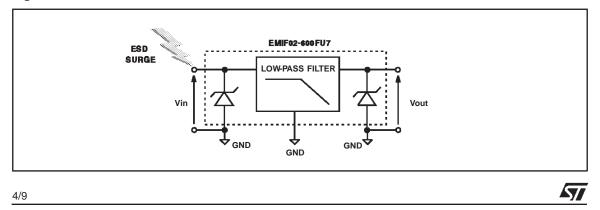
This confirms the very low remaining voltage across the device to be protected. It is also important to note that in this approximation the parasitic inductance effect was not taken into account. This could be few tenths of volts during few ns at the Vin side. This parasitic effect is not present at the Vout side due the low current involved after the resistance R.

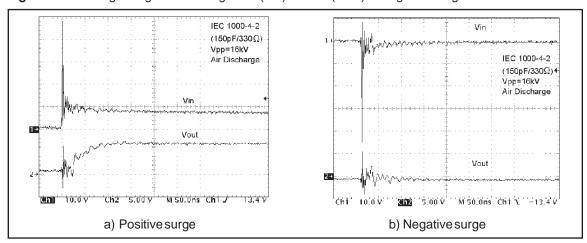
The measurements shown here after illustrate very clearly (Fig. A5a) the high efficiency of the ESD protection :

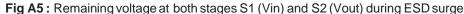
- no influence of the parasitic inductances on Vout stage

- Vout clamping voltage very close to  $V_{\mbox{\scriptsize BR}}$ 

Fig A4 : Measurement conditions





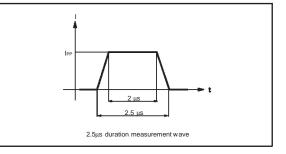


Please note that the EMIF02-600FU7 is not only acting for positive ESD surges but also for negative ones. For these kind of disturbances it clamps close to ground voltage as shown in Fig. A5b.

#### NOTE: DYNAMIC RESISTANCE MEASUREMENT

#### Fig A6 : Rd measurement current wave

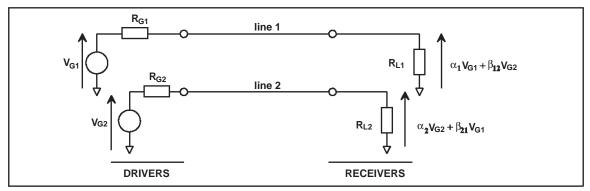
As the value of the dynamic resistance remains stable for a surge duration lower than  $20\mu$ s, the  $2.5\mu$ s rectangular surge is well adapted. In addition both rise and fall times are optimized to avoid any parasitic phenomenon during the measurement of Rd.



#### **CROSSTALK BEHAVIOR**



Fig A7 : Crosstalk phenomena



The crosstalk phenomena are due to the coupling between 2 lines. The coupling factor ( $\beta_{12}$  or  $\beta_{21}$ ) increases when the gap across lines decreases, particularly in silicon dice. In the example above the expected signal on load R<sub>L2</sub> is  $\alpha_2 V_{G2}$ , in fact the real voltage at this point has got an extra value  $\beta_2 1 V_{G1}$ . This part of the V<sub>G1</sub> signal represents the effect of the crosstalk phenomenon of the line 1 on the line 2. This phenomenon has to be taken into account when the drivers impose fast digital data or high frequency analog signals in the disturbing line. The perturbed line will be more affected if it works with low voltage signal or high load impedance (few k $\Omega$ ). The following chapters give the value of both digital and analog crosstalk.

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## 2- Digital Crosstalk

Fig A8 : Digital crosstalk measurement

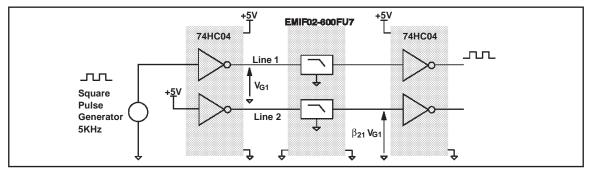
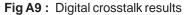
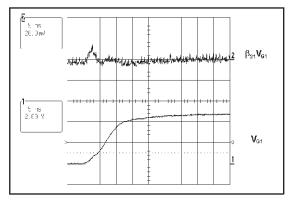


Figure A8 shows the measurement circuit used to quantify the crosstalk effect in a classical digital application.

Figure A9 shows that in such a condition signal from 0 to 5V and rise time of 10 ns, the impact on the disturbed line is less than 20mV peak to peak. No data disturbance was noted on the concerned line. The same results were obtained with falling edges.





# 3- Analog Crosstalk

Fig A10: Analog crosstalk measurement

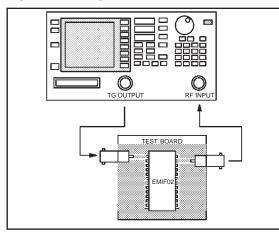


Fig A11 : Typical analog crosstalk result

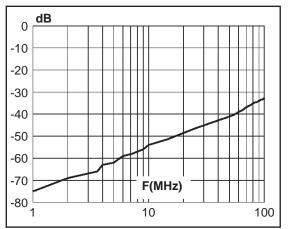


Figure A10 gives the measurement circuit for the analog application. In figure A11, the curve shows the effect of cell 1/24 on cell 2/23, no difference was found with other couples of adjacent cells. In usual frequency range of analog signals (up to 100MHz) the effect on disturbed line is less than -32 dBm.

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## **PSPICE MODEL**

Fig A12: PSpice model of one EMIF02-600FU7 cell

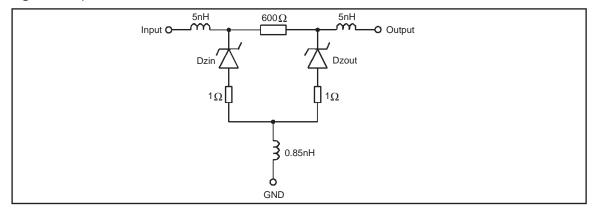


Figure A12 shows the PSpice model of one cell of the EMIF02-600FU7. In this model, the clamping diodes (Dzin and Dzout) are defined by the following PSpice parameters :

RS = 0.55 Cjo = 100p M = 0.3333 VJ = 0.6 BV = 7IBV = 1u

This model is available for frequency simulation and for ambient temperature of 27°C.

The comparison between the PSpice simulation and the measured frequency response is given in figáA13. This shows that the PSpice model is very close to the product behavior.

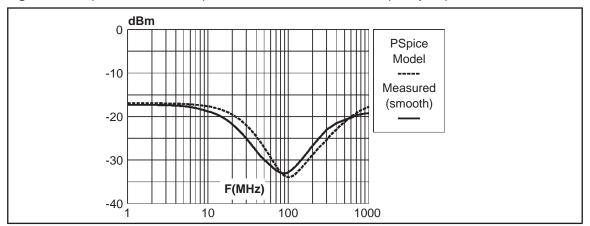
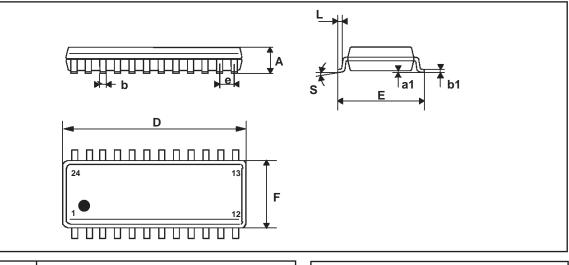


Fig A13 : Comparison between PSpice simulation and measured frequency response

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#### PACKAGE MECHANICAL DATA SSOP24

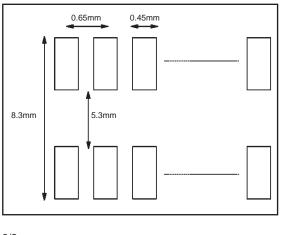


	DIMENSIONS					
REF.	Millimeters		Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	1.73	1.86	2.00	0.068	0.073	0.079
a1	0.05		0.25	0.002		0.010
b	0.25		0.35	0.010		0.014
b1	0.10		0.35	0.0035		0.014
D	8.07	8.20	8.33	0.317	0.322	0.328
Е	7.60		7.90	0.299		0.311
е		0.65			0.0256	
F	5.20		5.38	0.2047		0.2118
L	0.25		0.88	0.010		0.0347
S			8°r	nax		

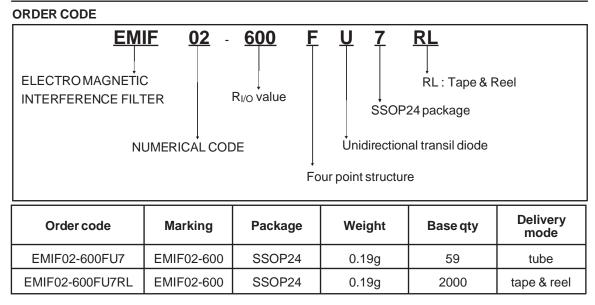
Mechanical specifications			
Lead plating	Tin-lead		
Lead plating thickness	7μm min. 20 μm max.		
Lead material	Copper alloy		
Lead coplanarity	0.08mm max.		
Body material	Molded epoxy		
Flammability	UL94V-0		

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# **RECOMMENDED FOOTPRINT**



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